

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	15	("20020037435" "20020060091" "20020164488" "20030098632" "20040070946" "20040074951" "20040089928" "20040207072" "20050214518" "4693409" "5807626" "6013357" "6033787" "6485816" "6569514"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 09:22
S2	3642	361/704.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 09:30
S3	1	361/704.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 09:53
S4	1	361/705-709.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 09:54
S5	0	361/717.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:06
S6	1	361/736.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:06
S7	1	361/746.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:06
S8	1	428/650.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:07
S9	3	428/210.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:08
S10	10	("3892835" "4770953" "4849292" "4920640" "5063121" "5085923" "5326623" "5363278" "5439856").PN. OR ("6013357").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:14
S11	8	428/209.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:14

S12	13	("4668532" "4786528" "5382333" "5439986" "5652042" "5670250" "5888627" "6060150" "6214455" "6355131" "6524717").PN. OR ("6692818").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:18
S13	0	S10 (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:19
S14	1	428/910.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:19
S15	0	165/80.2.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:19
S16	0	165/104.33.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:19
S17	2	257/705-707.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:19
S18	0	257/713.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:20
S19	2	257/720.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:20
S20	0	427/96.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:20
S21	0	62/259.2.ccls. (hon\$3 (release near2 agent))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:20
S22	2	"361"/\$.ccls. (hon\$3 (release near2 agent) boron)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:21
S23	41	"428"/\$.ccls. (hon\$3 (release near2 agent) boron)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:21
S24	25	S23 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:21
S25	17	S24 (ceramic metal)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:22
S26	18	"427"/\$.ccls. (hon\$3 (release near2 agent) boron)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:28

S27	14	S26 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:28
S28	12	S27 (ceramic metal)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:28
S29	1	S28 (braz\$3 join\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:29
S30	0	"165"/\$.ccls. (hon\$3 (release near2 agent) boron)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:29
S31	7	"257"/\$.ccls. (hon\$3 (release near2 agent) boron)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:29
S32	2	S31 (braz\$3 join\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:29
S33	1474	"62"/\$.ccls. (braz\$3 join \$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:29
S34	0	S33 (hon\$3 (release near2 agent) boron)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:30
S35	6	(braz\$3 join\$3 hon\$3 (release near2 agent) boron)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:30
S36	12	((substrate or board or PCB) ceramic metal (release near2 agent) boron aluminum (nitrogen or nitride) join \$3 honing)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:36
S37	269	"361"/\$.ccls. ((power near2 module) (base) (board or substrate) ceramic aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:38
S38	2	S37 honing	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:38
S39	14	S37 boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:38
S40	1	S39 (release near2 agent)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:39
S41	7	((agent with boron) (power near2 module) (base) (board or substrate) ceramic aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:39

S42	65	"361"/\$.ccls. (braz\$3 (power near2 module) (base near2 (plate or sheet or layer)) (board or substrate) ceramic aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:40
S43	0	S42 boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:41
S44	19	(boron (attach or join\$3) braz\$3 (power near2 module) (base near2 (plate or sheet or layer)) (board or substrate) ceramic aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:41
S45	19	S44 nitride	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:42
S46	1	(10/087566).APP.	USPAT; USOCR	AND	ON	2009/01/21 10:44
S47	11	("20010017770" "3994430" "4222774" "5213877" "5707715" "5807626" "5965193" "6033787" "6122170" "6153025" "6297549"). PN. OR ("7276292"). URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:45
S48	23	("4611745" "5258887" "5291065" "5394011" "5490627" "5539254" "5561321" "5654586" "5850104" "5949649" "5956231"). PN. OR ("6122170"). URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:45
S49	24	("4770953" "5011732" "5130498" "5145540" "5213877" "5529852" "5616421" "5675474"). PN. OR ("6033787"). URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:45
S50	32	("3994430" "4056650" "4082869" "4104417" "4129243" "4693409" "4849292" "5130498" "5213877" "5262203"). PN. OR ("5965193"). URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:45

S51	25	("4634041" "4657825" "4693409" "4835344" "4849292" "4919731" "5328751" "5354415" "5561321").PN. OR ("5807626").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:46
S52	21	("3927815" "4672739" "4781970" "4979015").PN. OR ("5213877").URPN.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 10:46
S53	43	(S47 or S48 or S49 or S50 or S51 or S52) aln	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:47
S54	11	S53 boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:47
S55	44	(US-20050214518-\$ or US-20040207072-\$ or US-20040089928-\$ or US-20040074951-\$ or US-20040070946-\$ or US-20030098632-\$ or US-20020164488-\$ or US-20020060091-\$ or US-20020037435-\$ or US-20070274047-\$ or US-20080248326-\$ or US-20040071946-\$ or US-20030186005-\$ or US-20020026752-\$ or US-20060108601-\$ or US-20050141828-\$ or US-20050130342-\$).did. or (US-6569514-\$ or US-6485816-\$ or US-6033787-\$ or US-6013357-\$ or US-5807626-\$ or US-4693409-\$ or US-7375286-\$ or US-6692818-\$ or US-6726996-\$ or US-4313995-\$ or US-5888627-\$ or US-7408258-\$ or US-5985462-\$ or US-5613794-\$ or US-7256431-\$ or US-6122170-\$ or US-5965193-\$ or US-5707715-\$ or US-5213877-\$ or US-3994430-\$ or US-5354415-\$ or US-5561321-\$ or US-	US-PGPUB; USPAT	AND	ON	2009/01/21 10:48

		7270885-\$ or US-7393596-\$ or US-7255931-\$ or US-6689498-\$).did. or (US-5130498-\$).did.				
S56	0	S55 (grain strain braz\$3 (power near2 module) (base near2 (plate or sheet or layer)) (board or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:49
S57	1	(grain strain braz\$3 (power near2 module) (base near2 (plate or sheet or layer)) (board or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:49
S58	2	(honing (power near2 module) (base near2 (plate or sheet or layer)) (board or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:50
S59	14	((join\$3 or attach) SAME (hon\$3 or grind\$3)) (power near2 module) (base near2 (plate or sheet or layer)) (board or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:51
S60	2	S59 (boron aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:51
S61	103517	(releas\$3 near2 agent)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:52
S62	10677	S61 boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:52
S63	8175	S62 aluminum	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:52
S64	2449	S63 ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:52
S65	811	S64 (metal near3 (base or layer or sheet or plate))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:52
S66	575	S65 (board or substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:53
S67	36	S66 (crystal grain strain)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:53
S68	19	S67 braz\$3	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:53

S69	1533	((join\$3 with (metal with ceramic)) (plate or layer) braz\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:54
S70	296	S69 (grind\$3 or hon\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:55
S71	138	S70 boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:55
S72	124	S71 aluminum	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:55
S73	5	S72 (power near2 module)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 10:59
S74	3705	(grain strain crystal 40%)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:05
S75	2308	S74 (substrate or board)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:05
S76	303	S75 (braz\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:05
S77	139	S76 (boron aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:06
S78	0	S77 (grain SAME strain SAME crystal SAME40%)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:06
S79	0	S77 (grain SAME strain SAME crystal SAME 40%)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:06
S80	36	(grain SAME strain SAME crystal SAME 40%)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:06
S81	46	S77 ((plate or sheet or layer) with join\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:08
S82	2	((joint near2 surface) (release near2 agent) honing damage)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:17
S83	6	((joint near2 surface) (release near2 agent) honing)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:18
S84	103	((power near2 module) (base near2 plate) AIN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:26

S85	92	S84 ceramic	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:26
S86	41	S85 join\$3	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:26
S87	28	S86 braz\$3	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:29
S88	15	S84 (honing or grind\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:30
S89	257	((peak near2 height) WITH (boron or silicon or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:32
S90	2	S89 ((power near2 module) (base near2 plate) AlN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:33
S91	5	S89 braz\$3	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:33
S92	12	S89 ((peak near2 height) WITH (formula or expression))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:34
S93	3	"I353" boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:34
S94	320	"I35" boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:34
S95	4	S92 boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:34
S96	102	S89 (x-ray or xray or (x adj ray))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:35
S97	2	S96 ((power near2 module) (base near2 plate) AlN)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:35
S98	0	((measure with (x-ray or xray or (x adj ray))) crystal strain grain (ceramic with metal with (adhe\$4 or join\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:36
S99	137	((measure with (x-ray or xray or (x adj ray))) crystal strain grain)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:37
S100	0	S99 ((peak near2 height) WITH (boron or silicon or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:37

S101	2	"20020164488"	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:38
S102	10	((thermal or temperature) near2 cycle) braz\$3 ((ceramic metal) WITH join) (power near2 (module or semiconductor)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:40
S103	187	((TOSHI YUKI) near2 (NAGASE)).INV.	EPO; JPO; DERWENT	AND	ON	2009/01/21 11:41
S104	17	((TOSHI YUKI) near2 (NAGASE)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 11:41
S105	79	((YOSHI YUKI) near2 (NAGATOMO)).INV.	EPO; JPO; DERWENT	AND	ON	2009/01/21 11:42
S106	11	((YOSHI YUKI) near2 (NAGATOMO)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 11:42
S107	66	((KAZUAKI) near2 (KUBO)).INV.	EPO; JPO; DERWENT	AND	ON	2009/01/21 11:42
S108	13	((KAZUAKI) near2 (KUBO)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 11:42
S109	95	((TAKESHI) near2 (NEGISHI)).INV.	EPO; JPO; DERWENT	AND	ON	2009/01/21 11:42
S110	10	((TAKESHI) near2 (NEGISHI)).INV.	US-PGPUB; USPAT; USOCR	AND	ON	2009/01/21 11:42
S111	19093	(mitsubishi near2 material).as.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:43
S112	210	S111 (S103 or S104 or S105 or S106 or S107 or S108 or S109 or S110)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:43
S113	1	S112 (((thermal or temperature) near2 cycle) braz\$3 ((ceramic metal) WITH join) (power near2 (module or semiconductor)))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:43
S114	9	(S103 or S104 or S105 or S106 or S107 or S108 or S109 or S110) ((join\$3 with (metal with ceramic)) (plate or layer) braz\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:44
S115	2	(S103 or S104 or S105 or S106 or S107 or S108 or S109 or S110) (aln boron grain strain)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:45
S116	2	S111 (aln boron grain strain)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:45

S117	2	S112 (peak near2 height)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:47
S118	973	((peak near2 height) with (b or boron))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:47
S119	15	S118 (kappa alpha)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:47
S120	5	S118 (power near2 module)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:48
S121	1000	361/736.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:57
S122	91	361/746.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:57
S123	0	(S121 or S122) ((base near2 plate) (power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:58
S124	1	(S121 or S122) ((power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:58
S125	0	361/704.ccls. ((power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:59
S126	0	361/706.ccls. ((power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 11:59
S127	121	361/706.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:00
S128	1648	428/210.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:01
S129	3622	428/209.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:01
S130	2504	428/910.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:01

S131	1	((power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:01
S132	36	((power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:01
S133	10	S132 (crystal or grain or strain).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:02
S134	1015	428/650.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:05
S135	2	S134 ((power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:05
S136	0	"361"/\$.ccls. (crystal grain strain (power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:05
S137	0	"428"/\$.ccls. (crystal grain strain (power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:05
S138	0	(crystal grain strain (power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:05
S139	0	(crystal grain (power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:06
S140	3	(grain (power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:06

S141	1	"428"/\$.ccls. ((crystal or strain or grain) (plate or layer) metal ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:07
S142	0	"361"/\$.ccls. ((crystal or strain or grain) (plate or layer) metal ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:07
S143	2	((crystal or strain or grain) (plate or layer) metal ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:07
S144	3	((crystal or strain or grain) ((plate or layer) with (metal ceramic)) (power near2 (semiconductor or module)) (board or substrate)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:08
S145	4	((join\$3) (release near2 agent) boron (aluminum or silicon)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:09
S146	6	((substrate or board) (join \$3) ((release or agent) with boron) (aluminum or silicon)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:09
S147	104	((substrate or board) (join \$3) AlN).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:10
S148	19	S147 boron	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:10
S149	14	S148 (ceramic metal)	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:11
S150	302	361/708.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:22

S151	0	361/708.ccls. ((crystal or strain or grain) ((plate or layer) near3 metal) ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:23
S152	1	361/708.ccls. ((crystal or strain or grain) ((plate or layer) near3 metal) ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:23
S153	322	((crystal or strain or grain) ((plate or layer) near3 metal) ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:23
S154	3	S153 honing	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:23
S155	0	361/739.ccls. ((crystal or strain or grain) ((plate or layer) near3 metal) ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:27
S156	0	361/739.ccls. ((crystal or strain or grain) ((plate or layer) near3 metal) ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:27
S157	74	361/739.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:28
S158	206	361/771.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:30
S159	2320	361/760.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:30

S160	3	(S158 or S159) ((crystal or strain or grain) ((plate or layer) near3 metal) ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:31
S161	0	(S158 or S159) ((crystal or strain or grain) ((plate or layer) near3 metal) ceramic (power near2 (semiconductor or module)) (board or substrate) boron (silicon or aluminum)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:31
S162	0	(S158 or S159) (crystal grain strain (power near2 (semiconductor or module)) (board or substrate) boron aluminum).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO	AND	ON	2009/01/21 12:31

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